



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP40286	REV: A	SUN REV: Not In VersionControl
	TID #: PMP40286		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/20/2017 3:28:08 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP40286	REV: A	SUN REV: Not In VersionControl
	TID #: PMP40286		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/20/2017 3:28:11 PM		TEXAS INSTRUMENTS

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